2SA0885 (2SA885)

Silicon PNP epitaxial planar type

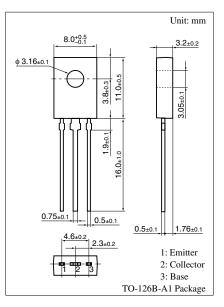
For low-frequency power amplification Complementary to 2SC1846

Features

- Output of 3 W can be obtained by a complementary pair with 2SC1846
- TO-126B package which requires no insulation plate for installation to the heat sink

Absolute Maximum Hatings $T_{\rm C} = 25 {\rm C}$						
Parameter	Symbol	Rating	Unit			
Collector to base voltage	V _{CBO}	-45	V			
Collector to emitter voltage	V _{CEO}	-35	V			
Emitter to base voltage	V _{EBO}	-5	V			
Peak collector current	I _{CP}	-1.5	А			
Collector current	I _C	-1	А			
Collector power dissipation	P _C	1.2 *1	W			
		5 * ²				
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			

Absolute Maximum Ratings $T_C = 25^{\circ}C$



Note) *1: Without heat sink

*2: With a $100 \times 100 \times 2$ mm A1 heat sink

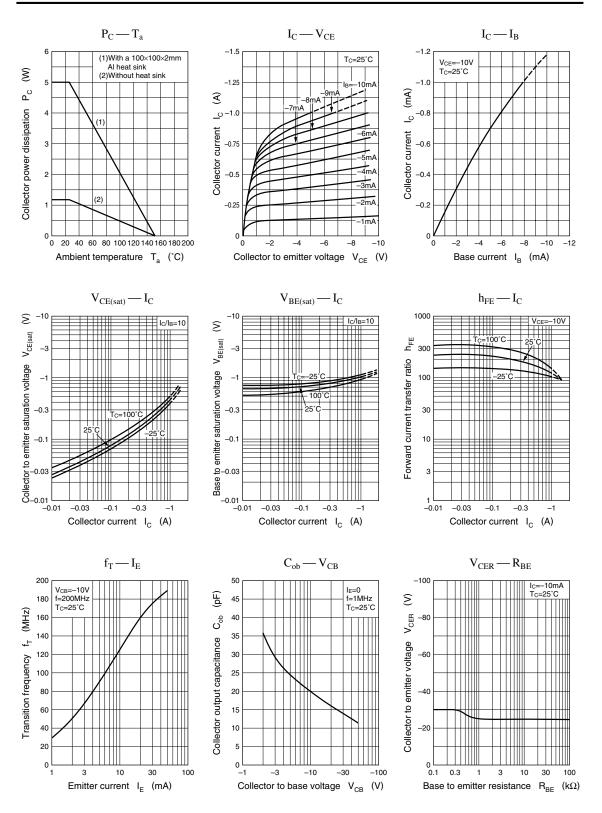
Electrical Characteristics $T_C = 25^{\circ}C$

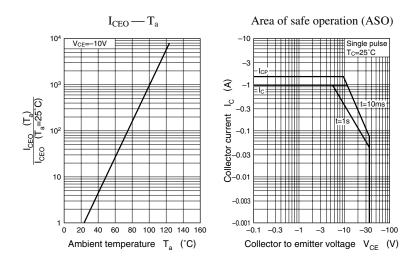
Parameter	Symbol	Conditions	Min	Тур	Мах	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = -20 V, I_E = 0$			- 0.1	μΑ
	I _{CEO}	$V_{CE} = -20 V, I_B = 0$			-100	μΑ
Emitter cutoff current	I_{EBO}	$V_{EB} = -5V, I_C = 0$			-10	μΑ
Collector to base voltage	V _{CBO}	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$	-45			V
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-35			V
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -10 \text{ V}, I_C = -500 \text{ mA}$	85		340	
	h _{FE2}	$V_{CE} = -5 V, I_C = -1 A$	50			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -500 \text{ mA}, I_{\rm B} = -50 \text{ mA}$			- 0.5	V
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		20	30	pF

Note) *: Rank classification

Rank	Q	R	S
h _{FE1}	85 to 170	120 to 240	170 to 340

Note.) The Part number in the Parenthesis shows conventional part number.





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